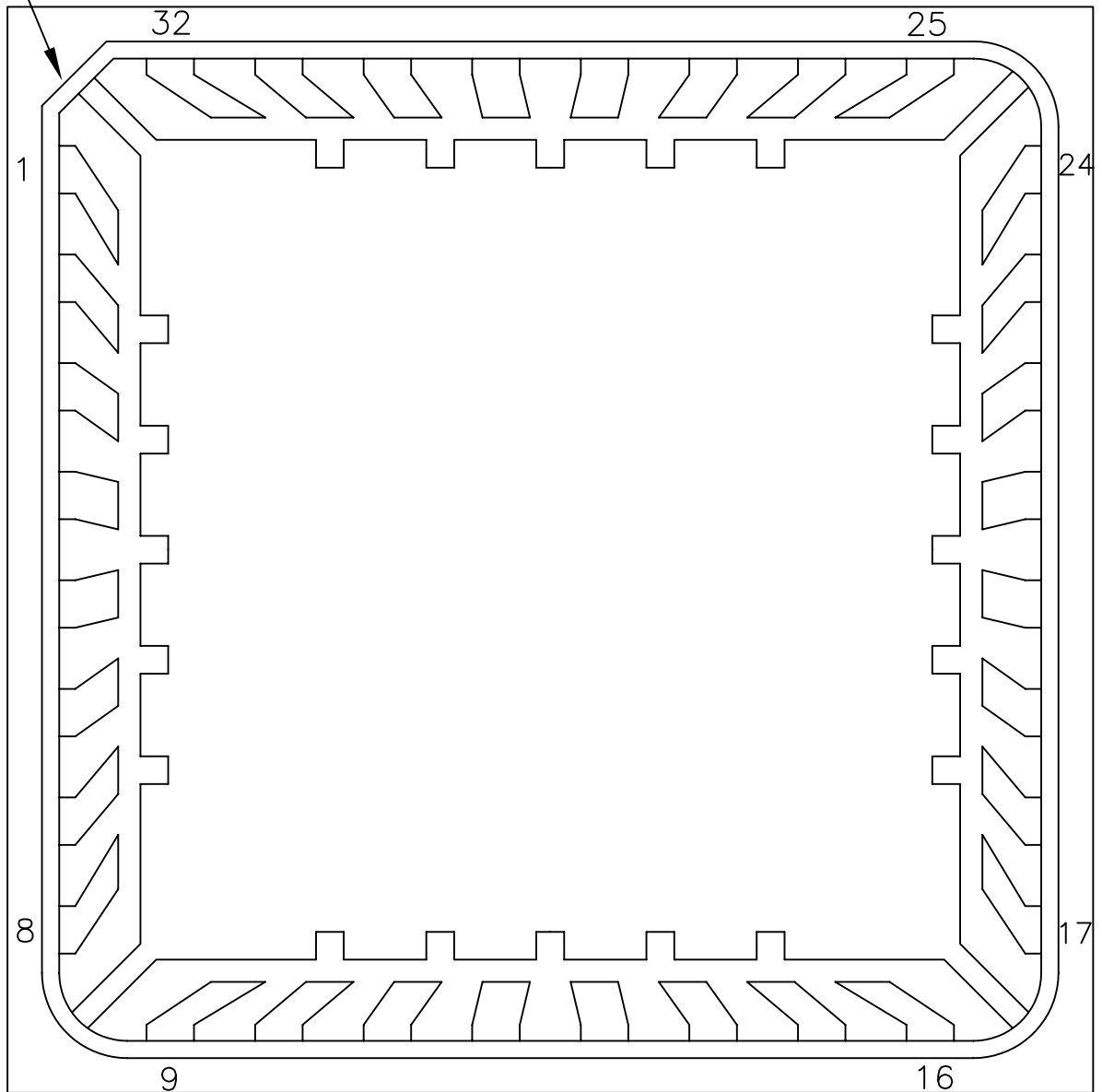


PIN #1 IDENTIFIER



DEVICE TYPE:				SEMPAC, INC. Open-Pak™ Technologies www.sempac.com 568 E. WEDDELL DRIVE, SUITE 5 SUNNYVALE, CALIFORNIA 94089 PHONE: (408) 400-9002 FAX: (408) 400-9006					
CUSTOMER:			DIE SIZE:						
WIRE TYPE/ SIZE:			NO. OF WIRES:						
THIRD ANGLE PROJECTION	REVISIONS					32 Lead 8mm x 8mm MLP Open-Pak Bonding Diagram			
	ECN NO.	DATE	DESCRIPTION	APPROVED					
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETER DO NOT SCALE DRAWING	10632	3/13/06	INITIAL RELEASE	D.BENANDO					
DRAWN BY: GRIFFITTS APP BY: P. FLASKERUD	DATE: 3/13/06 DATE: 3/13/06	PACKAGE SIZE: 8.00mm x 8.00mm DIE PAD SIZE: 6.040mm x 6.040mm	SIZE: A SCALE: 20X	PART NO.: MLP8X8-32-OP-01 CAD FILE: MLP8X8-32-OP-01-B-R1.DWG	REV: 1 SHEET: 1 OF 1				